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(54) Title: METHOD OF LAMINATING AN INTERPOSER FOR DIE TRANSFER SUBSTRATES

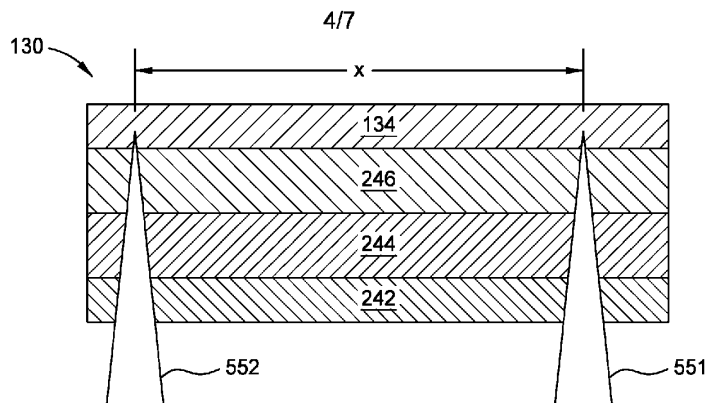


FIG. 5A

(57) **Abstract:** Embodiments of the present disclosure generally relate to LED pixels and methods of fabricating LED pixels. The device includes a lamination module. The lamination module includes a polymer film roll configured to supply a polymer film to the lamination module, a bottom liner recovery roller, a top liner recovery roller, a cutting mechanism, a substrate source, a conveyor system, and a plurality of film rollers. The polymer film includes one or more polymer layers, a top liner, and a bottom liner. The cutting mechanism is configured to cut the one or more polymer layers and the top liner. The cutting mechanism comprises a first blade and a second blade. A space between the first blade and the second blade is less than about 10 cm. The substrate source is configured to supply a substrate.

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